



DMNH6008SCT

N-CHANNEL ENHANCEMENT MODE MOSFET

Product Summary

BV _{DSS}	R _{DS(ON)}	I _D T _C = +25°C	
60V	$8.0 \text{m}\Omega @ V_{GS} = 10V$	130A	

Description

This new generation MOSFET is designed to minimize the on-state resistance (R_{DS(ON)}), yet maintain superior switching performance, making it ideal for high-efficiency power management applications.

Applications

- Motor Control
- Backlighting
- DC-DC Converters
- Power Management Functions

Features

- Rated to +175°C Ideal for High Ambient Temperature Environments
- 100% Unclamped Inductive Switching Ensures More Reliable and Robust End Application
- Low Input Capacitance
- Low Input/Output Leakage
- Lead-Free Finish; RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- Qualified to AEC-Q101 Standards for High Reliability
- An Automotive-Compliant Part is Available Under Separate Datasheet (<u>DMNH6008SCTQ</u>)

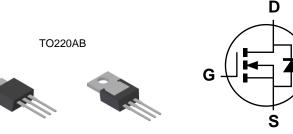
Mechanical Data

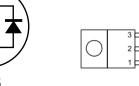
- Case: TO220AB
- Case Material: Molded Plastic, "Green" Molding Compound.
 UL Flammability Classification Rating 94V-0
- Terminals: Matte Tin Finish Annealed over Copper Leadframe.
 Solderable per MIL-STD-202, Method 208 (63)

Top View

Pin Out Configuration

- Terminal Connections: See Diagram Below
- Weight: 1.85 grams (Approximate)





Ordering Information (Note 4)

Top View

Ī	Part Number	Case	Packaging
ı	DMNH6008SCT	TO220AB	50 pieces/tube

Notes:

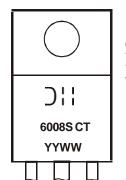
- 1. EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant. All applicable RoHS exemptions applied.
- See http://www.diodes.com/quality/lead_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.

Equivalent Circuit

- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at http://www.diodes.com/products/packages.html.

Bottom View

Marking Information



6008SCT = Product Type Marking Code YYWW = Date Code Marking YY = Last Two Digits of Year (ex: 16 = 2016) WW = Week (01 to 53)



Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit		
Drain-Source Voltage			V_{DSS}	60	V
Gate-Source Voltage			V _{GSS}	20	V
Continuous Drain Current (Note 5) V _{GS} = 10V	Steady State	$T_{C} = +25^{\circ}C$ $T_{C} = +100^{\circ}C$	I _D	130 90	А
Pulsed Drain Current (10µs Pulse, Duty Cycle = 1%)			I _{DM}	200	A
Maximum Continuous Body Diode Forward Current (Note 5)			Is	80	A
Avalanche Current (Note 6) L=0.1mH			I _{AS}	62	Α
Avalanche Energy (Note 6) L=0.1mH			E _{AS}	190	mJ

Thermal Characteristics

Characteristic	Symbol	Value	Unit
Power Dissipation (Note 5) $T_C = +25^{\circ}C$ $T_C = +100^{\circ}C$	P _D	210 100	W
Thermal Resistance, Junction to Case (Note 5)	Rejc	0.7	°C/W
Operating and Storage Temperature Range	T _J , T _{STG}	-55 to +175	°C

Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition	
OFF CHARACTERISTICS (Note 7)							
Drain-Source Breakdown Voltage	BV _{DSS}	60	_	_	V	$V_{GS} = 0V, I_D = 250\mu A$	
Zero Gate Voltage Drain Current	IDSS	_	_	1	μA	V _{DS} = 48V, V _{GS} = 0V	
Gate-Source Leakage	I _{GSS}	_	_	±100	nA	$V_{GS} = \pm 16V, V_{DS} = 0V$	
ON CHARACTERISTICS (Note 7)							
Gate Threshold Voltage	V _{GS(TH)}	2		4	V	$V_{DS} = V_{GS}$, $I_D = 250\mu A$	
Static Drain-Source On-Resistance	R _{DS(ON)}	1	6.0	8.0	mΩ	$V_{GS} = 10V, I_D = 20A$	
Diode Forward Voltage	V_{SD}	1	0.7	1.2	V	$V_{GS} = 0V, I_{S} = 1A$	
DYNAMIC CHARACTERISTICS (Note 8)							
Input Capacitance	CISS	-	2,596	_		$V_{DS} = 30V, V_{GS} = 0V$ f = 1.0MHz	
Output Capacitance	Coss	-	437	_	pF		
Reverse Transfer Capacitance	C _{RSS}		118	_			
Gate Resistance	R_{G}	-	2.0	_	Ω	$V_{DS} = 0V, V_{GS} = 0V, f = 1.0MHz$	
Total Gate Charge (V _{GS} = 10V)	Q_{G}		21	_		V _{DD} = 30V, I _D = 20A	
Total Gate Charge (V _{GS} = 4.5V)	Q_{G}		40	_	nC		
Gate-Source Charge	Q_{GS}	1	8.3	_	IIC		
Gate-Drain Charge	Q_{GD}	1	11.8	_			
Turn-On Delay Time	t _{D(ON)}	-	5.7	_		$V_{DD} = 30V, V_{GS} = 10V,$ $R_{G} = 1\Omega, I_{D} = 20A$	
Turn-On Rise Time	t _R	_	5.0	_	20		
Turn-Off Delay Time	t _{D(OFF)}	_	15.6	_	ns		
Turn-Off Fall Time	t _F	_	3.4	_			
Reverse Recovery Time	t _{RR}	_	33	_	ns	1 000 11/14 1000/	
Reverse Recovery Charge	Q _{RR}	_	33	_	nC I _F = 20A, di/dt = 100A/µs		

Notes:

- 5. Device mounted on FR-4 PC board, with minimum recommended pad layout, single sided.
- 6. I_{AS} and E_{AS} rating are based on low frequency and duty cycles to keep $T_J = +25$ °C
- 7. Short duration pulse test used to minimize self-heating effect.
 8. Guaranteed by design. Not subject to product testing.



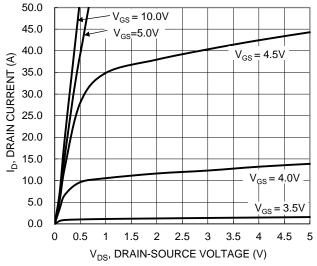


Figure 1. Typical Output Characteristic

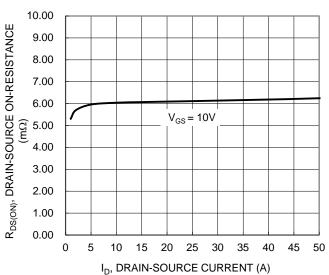


Figure 3. Typical On-Resistance vs. Drain Current and Gate Voltage

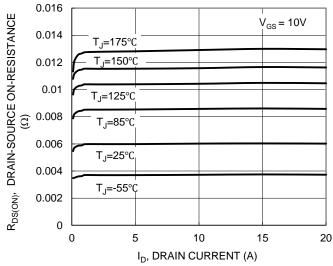


Figure 5. Typical On-Resistance vs. Drain Current and Temperature

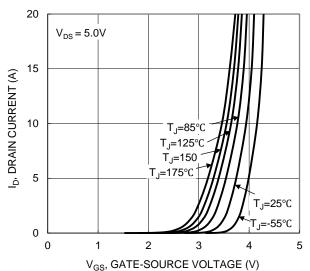


Figure 2. Typical Transfer Characteristic

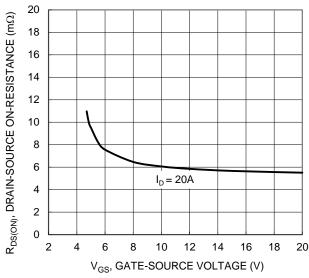


Figure 4. Typical Transfer Characteristic

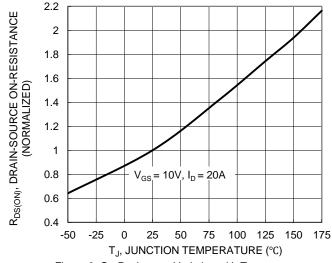


Figure 6. On-Resistance Variation with Temperature



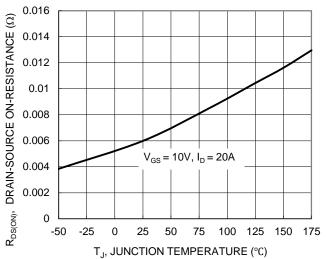


Figure 7. On-Resistance Variation with Temperature

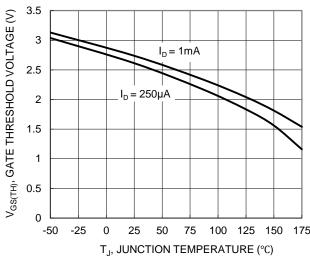
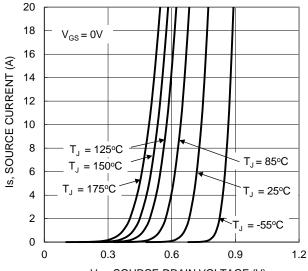
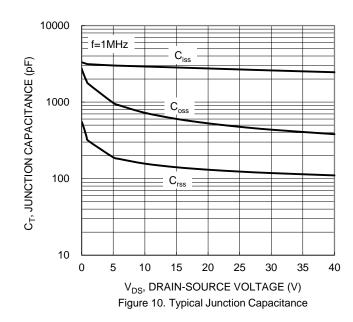
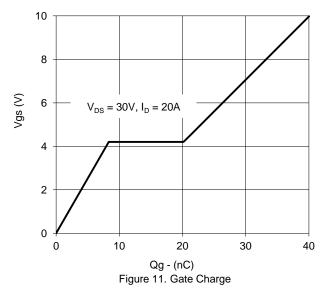


Figure 8. Gate Threshold Variation vs. Junction Temperature



V_{SD}, SOURCE-DRAIN VOLTAGE (V) Figure 9. Diode Forward Voltage vs. Current





100 ID, DRAIN CURRENT (A) P_W =10μs 10 $P_W = 1ms$ $P_W = 10 ms$ =100ms 1 $T_{J(Max)} = 175^{\circ}C$ $T_C = 25^{\circ}C$ Single Pulse DUT on infinite heatsink V_{GS}= 10V 0.01 0.1 10 100 V_{DS} , DRAIN-SOURCE VOLTAGE (V) Figure 12. SOA, Safe Operation Area

1000

 $R_{\text{DS}(\text{ON})}$ Limited



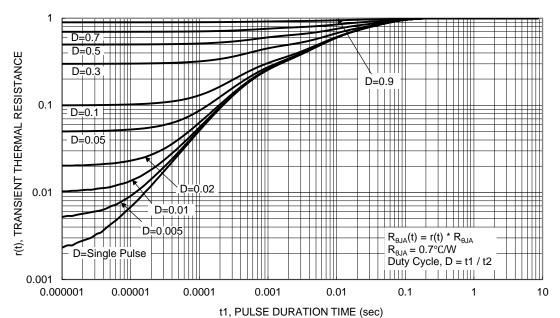


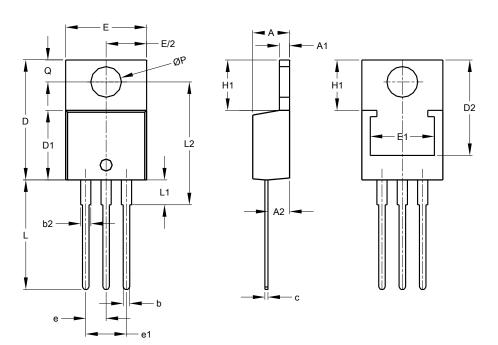
Figure 13. Transient Thermal Resistance



Package Outline Dimensions

Please see http://www.diodes.com/package-outlines.html for the latest version.

TO220AB



TO220AB						
Dim	Min	Max	Тур			
Α	3.56	4.82	-			
A 1	0.51	1.39	-			
A2	2.04	2.92	-			
b	0.39	1.01	0.81			
b2	1.15	1.77	1.24			
С	0.356	0.61	-			
D	14.22	16.51	-			
D1	8.39	9.01	-			
D2	11.45	12.87	-			
е	-	-	2.54			
e1	-	-	5.08			
Ε	9.66	10.66	-			
E1	6.86	8.89	-			
H1	5.85	6.85	-			
L	12.70	14.73	-			
L1	-	6.35	-			
L2	15.80	16.20	16.00			
Р	3.54	4.08	-			
Q	2.54	3.42	-			
All Dimensions in mm						



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